

Title (en)
A CONTROLLED CLEAVAGE PROCESS

Title (de)
KONTROLLIERTES SPALTUNGSVERFAHREN

Title (fr)
PROCEDE DE CLIVAGE CONTROLE

Publication
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Application
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Priority

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Abstract (en)
[origin: WO9852216A1] A technique for forming a film of material (12) from a donor substrate (10). The technique has a step of introducing energetic particles (22) in a selected manner through a surface of a donor substrate (10) to a selected depth (20) underneath the surface, where the particles have a relatively high concentration to define a donor substrate material (12) above the selected depth and the particles for a pattern at the selected depth. An energy source such as pressurized fluid is directed to a selected region of the donor substrate to initiate a controlled cleaving action of the substrate (10) at the selected depth (20), whereupon the cleaving action provides an expanding cleave front to free the donor material from a remaining portion of the donor substrate.

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IPC 8 full level
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